

DISPLAY Elektronik GmbH

DATA SHEET

LCD MODULE

DEM 16481 SYH-LY-CYR22

Product Specification

Version : 3

08/Jan/2018

GENERAL SPECIFICATION

MODULE NO. :

DEM 16481 SYH-LY-CYR22

CUSTOMER P/N

VERSION NO.	CHANGE DESCRIPTION	DATE
0	ORIGINAL VERSION	31.03.2004
1	CHANGED PCB DRAWING AND DESCRIPTION	30.07.2004
1.1.0	ORIGINAL VERSION	14.01.2008
1.1.1	CHANGE PCB DESCRIPTION	31.10.2008
2	CHANGE PCB DESCRIPTION	25.11.2008
3	Change the VDD from -0.3~+7.0 V to -0.3~+6V; VLCD from 3.0~10V to 3.0~ 7V in page6	08.01.2018

PREPARED BY: PS

DATE: 18.01.2018

APPROVED BY: MHO

DATE: 18.01.2018

CONTENTS

1. FUNCTIONS & FEATURES.....2

2. MECHANICAL SPECIFICATIONS2

3. BLOCK DIAGRAM3

4. EXTERNAL DIMENSIONS3

5. PIN ASSIGNMENT4

6. PCB DRAWING AND DESCRIPTION5

7. BACKLIGHT VOLTAGE & CURRENT6

8. DISPLAY DATA RAM6

9. MAXIMUM ABSOLUTE POWER RATINGS.....7

10. ELECTRICAL CHARACTERISTICS8

11. CONTROL AND DISPLAY COMMAND10

12. STANDARD CHARACTER PATTERN11

13. QUALITY DESCRIPTION12

14. MODULES ACCEPT QUALITY LEVEL (AQL).....13

15. RELIABILITY TEST.....13

16. LCD MODULES HANDLING PRECAUTIONS14

17. OTHERS14

1.FUNCTIONS & FEATURES

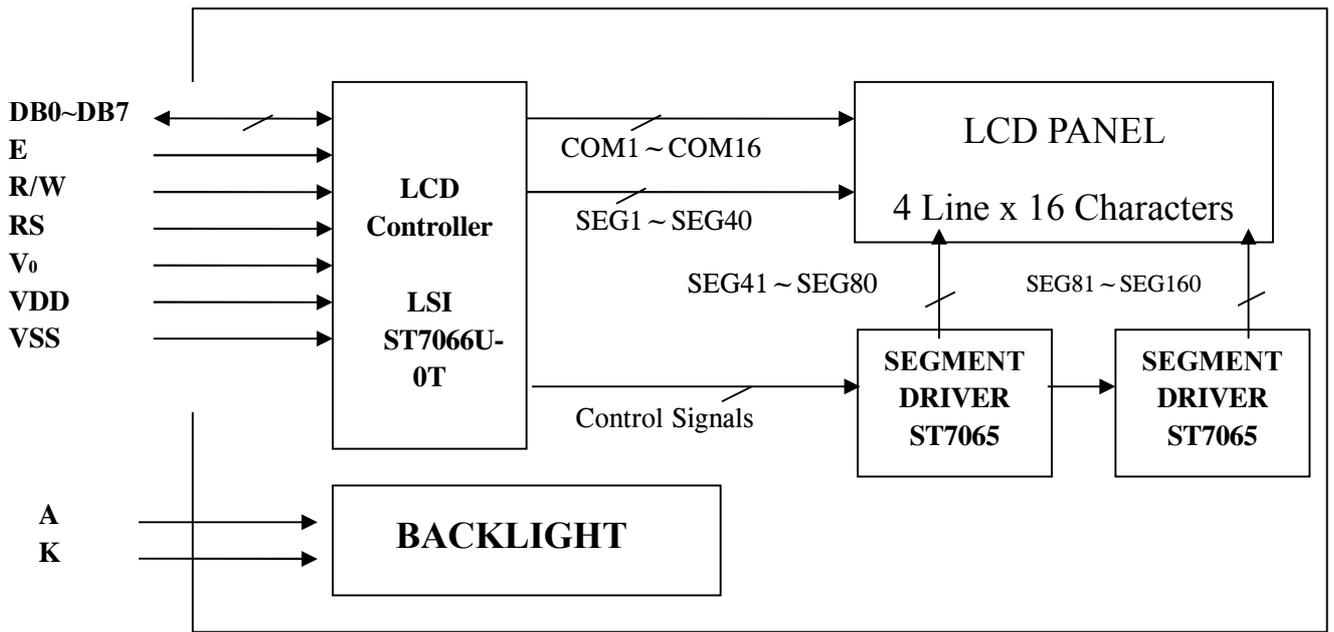
MODULE	LCD TYPE	Remark
MBCF16414B00	STN Yellow Green Transflective Positive Mode	ROHS Conformed

- Viewing Direction : 6 O'clock
- Driving Scheme : 1/16 Duty Cycle, 1/5 Bias
- Power Supply Voltage : 5.0 Volt (typ.)
- Backlight Color : Yellow Green
- VLCD Adjustable For Best Contrast : 4.5 Volt (typ.)
- Display contents : 16 x 4 Characters
- Operating Temperature : - 20°C to + 70°C
- Storage Temperature : - 30°C to + 80°C
- Internal Memory : CGROM (8,320 bits)
: CGRAM (64 x 8 bits)
: DDRAM (80 x 8 bits)
- CGROM : CGROM of the ST7066U-0T
- Interface : Easy Interface with a 4-bit or 8-bit MPU

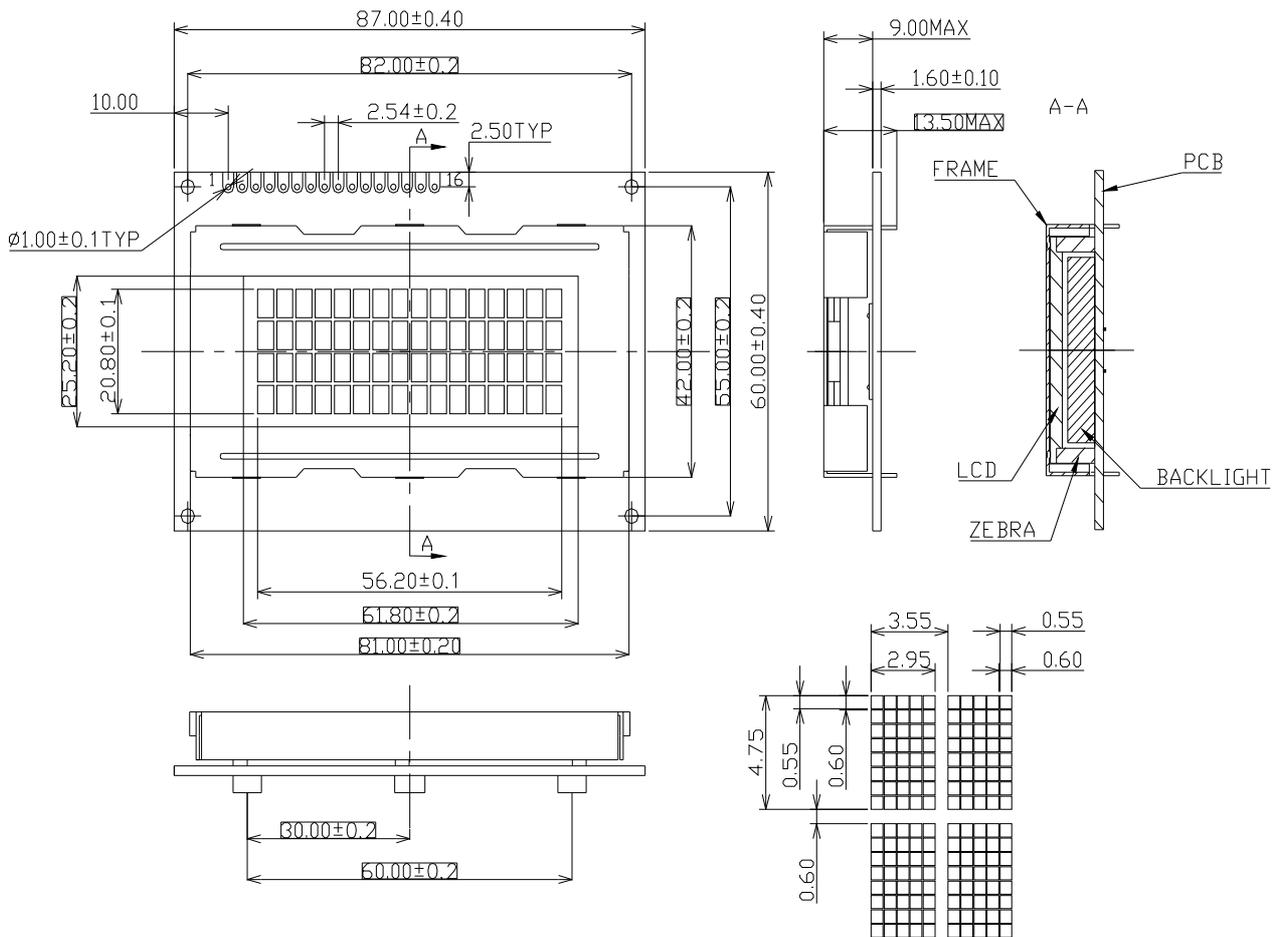
2. MECHANICAL SPECIFICATIONS

- Module Size : 87.00 x 60.00 x 13.50 mm
- Character Pitch : 3.55 x 5.35 mm
- Character Size : 2.95 x 4.75 mm
- Character Font : 5 x 8 dots
- Dot Size : 0.55 x 0.55 mm
- Dot Pitch : 0.60 x 0.60 mm
- Dot Gap : 0.05 mm

3. BLOCK DIAGRAM



4. EXTERNAL DIMENSIONS



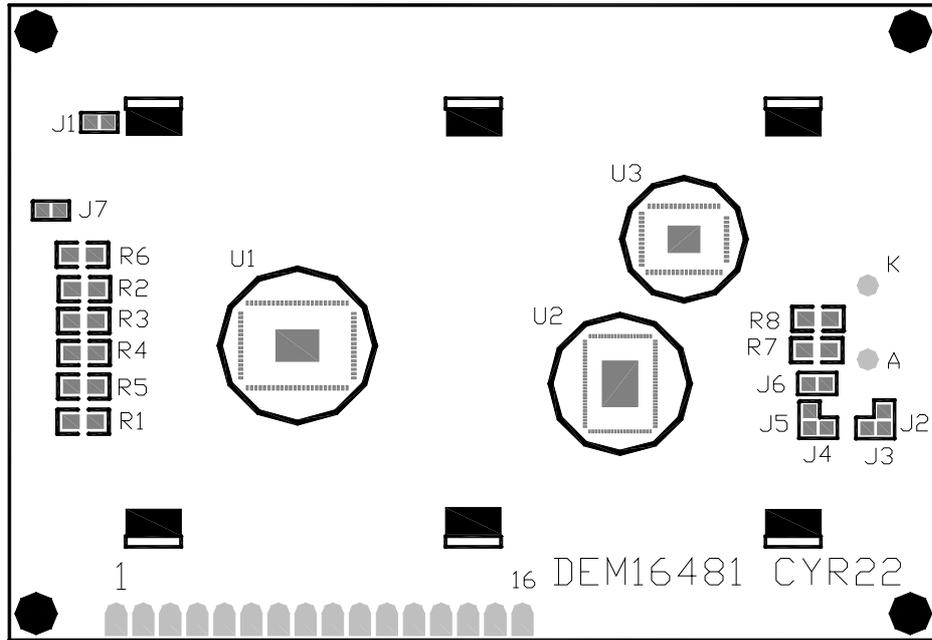
NOTES:

UNTOLERANCE IS ±0.5mm.

5. PIN ASSIGNMENT

Pin No.	Symbol	Function
1	VSS	Ground terminal of module.
2	VDD	Power terminal of module 5.0V.
3	V0	Power Supply for liquid crystal drive.
4	RS	Register select RS = 0...Instruction register RS = 1...Data register
5	R/W	Read /Write R/W = 1...Read R/W = 0...Write
6	E	Read/Write Enable Signal
7	DB0	Bi-directional data bus, data transfer is performed once, thru DB0 to DB7, in the case of interface data. Length is 8-bits; and twice, thru DB4 to DB7 in the case of interface data length is 4-bits. Upper four bits first then lower four bits.
8	DB1	
9	DB2	
10	DB3	
11	DB4	
12	DB5	
13	DB6	
14	DB7	
15	LED – (K)	Please also refer to 6. PCB drawing and description.
16	LED + (A)	Please also refer to 6. PCB drawing and description.

6. PCB DRAWING AND DESCRIPTION



Note1: In application module, R1 ~ R5=820 Ω , R6=91K Ω
 Note2: The part no. DEM16481 CYR22 is printed on the PCB.

DESCRIPTION:

6-1-1.The polarity of the pin 15 and the pin 16:

symbol	symbol state	J3,J5	J2,J4	LED Polarity	
				15 Pin	16 Pin
J2,J4	Each solder-bridge	Each open	Each closed	Anode	Cathode
J3,J5	Each solder-bridge	Each closed	Each open	Cathode	Anode

Note: In application module, J3=J5=closed, J2=J4= open

6-1-2.The metal-bezel is set on ground when the J1 is closed.

Note: In application module, J1=closed

6-1-3.The LED resistor can be bridged when the J6 is closed.

Note: In application module, J6=open

6-1-4.The R7 and the R8 are the LED resistor.

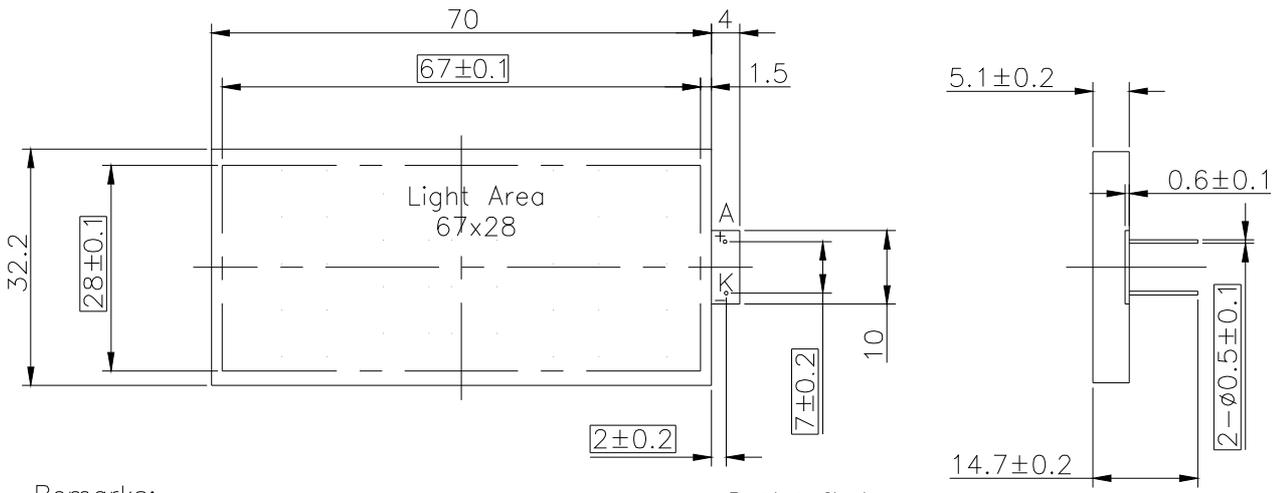
Note: In application module, R7=R8= 15 Ω

6-1-5. The mounting holes should be on ground when the J7 is solder-bridge.

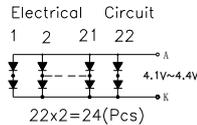
Note: In module application, J7=closed

7. BACKLIGHT & SWITCH (Ta=-20~+70°C)

	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
Forward Voltage	V _f	3.9	4.1	4.3	V	I _f = 220mA
Forward Current	I _f		330		mA	
Power Dissipation	P _d		1.42		W	I _f = 220mA
Reverse Voltage	V _R		10		V	V _f = 10 V
Reverse Current	I _R			0.26	mA	
Luminous Intensity	I _V	160	180		cd/m ²	I _f = 220mA
Luminous Uniformity		70			%	
Emission Wavelength	λ _P	569	572	575	nm	I _f =220mA Ta=25°C Each chip
Spectral Range	Δλ		30		nm	



- Remarks:
- 1.Unmarked tolerance is ±0.3
 - 2.The material comply with RoHs
 3. color: yellow green



8. DISPLAY DATA RAM (DDRAM)

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	← Display position
FIRST LINE	00	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	0F	← DDRAM Address
SECOND LINE	40	41	42	43	44	45	46	47	48	49	4A	4B	4C	4D	4E	4F	
FIRST LINE	10	11	12	13	14	15	16	17	18	19	1A	1B	1C	1D	1E	1F	
SECOND LINE	50	51	52	53	54	55	56	57	58	59	5A	5B	5C	5D	5E	5F	

9. MAXIMUM ABSOLUTE LIMIT

Item	Symbol	Standard value	Unit
Power supply voltage(1)	V_{DD}	-0.3~+6.0	V
Power supply voltage(2)	V_{LCD}	$V_{DD}-10.0\sim V_{DD}+0.3$	V
Input voltage	V_{IN}	-0.3~ $V_{DD}+0.3$	V
Operating temperature	T_{opr}	-20~+70	°C
Storage temperature	T_{stg}	-30~+80	°C

*Voltage greater than above may damage to the Circuit.

$V_{DD} > V1 > V2 > V3 > V4 > V5$

10. ELECTRICAL CHARACTERISTICS

10-1-1 DC Characteristics(VDD=4.5V~5.5V,Ta=-20~+70°C)

Item	Symbol	Standard Value			Test Condition	Unit
		MIN	TYP	MAX		
Operating Voltage	V _{DD}	4.5	5.0	5.5	-----	V
Supply Current	I _{DD1}	----	0.7	1.0	Ceramic oscillation fosc=250kHz	mA
	I _{DD2}	----	0.4	0.6	Resistor oscillation external clock operation fosc=270kHz	
LCD Driving Voltage	V _{LCD}	3.0	4.5	7.0	V _{DD} -V ₅ (1/5,1/4 Bias)	V

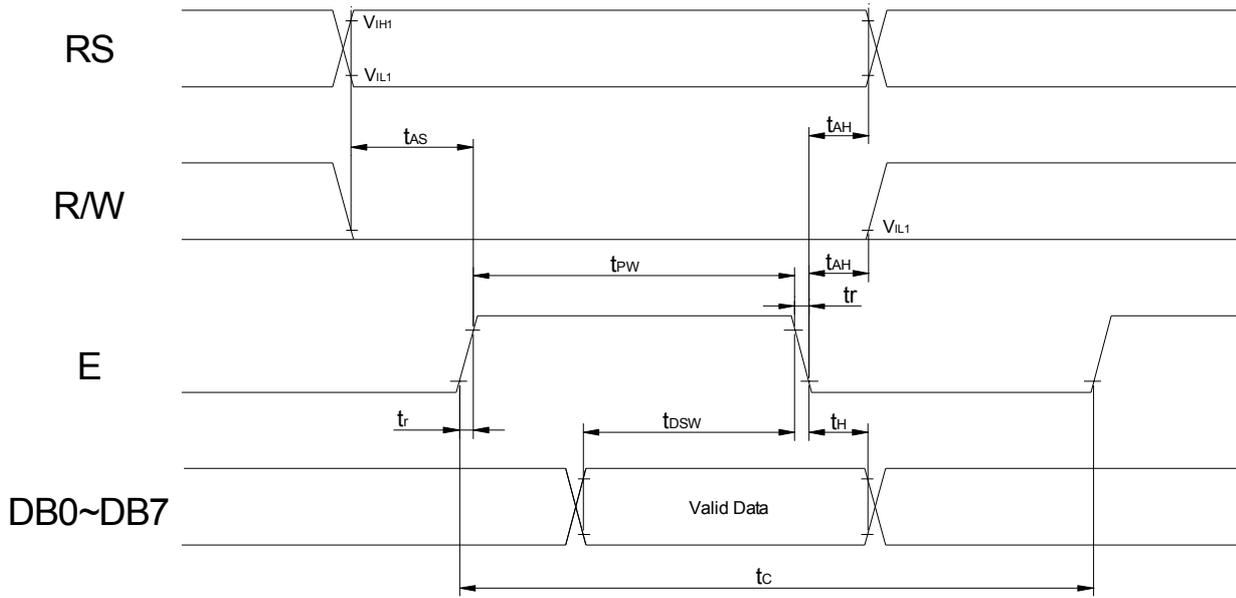
10-2-1 Write mode (writing data from MPU to module)

Item	Symbol	Min	Typ	Max	Unit	Test PIN
E Cycle Time	t _C	1200		---	--ns -	E
E Rise/Fall Time	t _R ,t _F	---		25	ns	E
E Pulse Width (High, Low)	t _w	140		---	ns	E
R/W and RS Setup Time	t _{su1}	0		---	-ns	R/W,RS,E
R/W and RS Hold Time	t _{H1}	10		---	--ns	R/W,RS,E
Data Setup Time	t _{su2}	40		---	--ns	DB0~DB7
Data Hold Time	t _{H2}	10		---	--ns	DB0~DB7

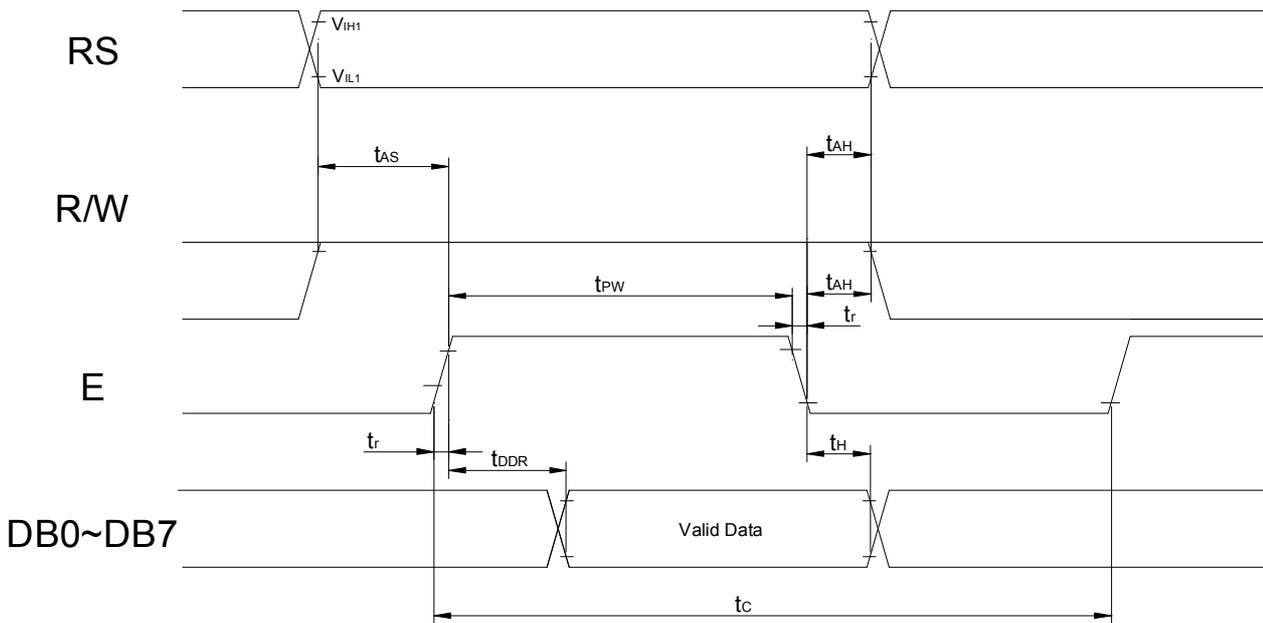
10-2-2 Read Mode (Reading Data From module to MPU)

Characteristic	Symbol	Min	Type	Max	Unit	Test PIN
E Cycle Time	t _C	1200	---	---	ns	E
E Rise Time	t _R	---	---	25	ns	E
E Fall Time	t _F	---	---	25	ns	E
E Pulse width	tp _w	140	---	---	ns	E
Address Setup Time	t _{AS}	0	---	---	ns	R/W,RS,E
Address Hold Time	t _{AH}	10	---	---	ns	R/W,RS,E
Data Setup Time	t _{DDR}	---	---	100	ns	DB0~DB7
Data Hold Time	t _H	10	---	---	ns	DB0~DB7

10-3-1 Write mode



10-3-2 Read mode



11. CONTROL AND DISPLAY COMMAND

Command	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Execution time (fosc=270KHz)	Remark
Clear Display	0	0	0	0	0	0	0	0	0	1	1.52ms	Write"20H" to DDRAM. And set DDRAM address to "00H" from AC
Return home	0	0	0	0	0	0	0	0	1	x	1.52ms	Set DDRAM address to "00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed.
Entry mode Set	0	0	0	0	0	0	0	1	I/D	S	37us	Sets cursor move direction and specifies display shift. These operations are performed during data write and read.
Display on/off control	0	0	0	0	0	0	1	D	C	B	37us	D=1: entire display on C=1: cursor on B=1: cursor position on
Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	x	x	37us	Set cursor moving and display shift control bit, and the direction, without changing DDRAM data.
function Set	0	0	0	0	1	DL	N	F	x	x	37us	DL: interface data is 8/4 bits N: number of line is 2/1 F: font size is 5x11/5x8
Set CGRAM address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	37us	Set CGRAM address in address counter
Set DDRAM address	0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	AC0	37us	Set DDRAM address in address counter
Read busy flag& address	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	0us	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.
Write data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	37us	Write data into internal RAM (DDRAM/CGRAM)
Read data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	37us	Read data from internal RAM (DDRAM / CGRAM)

Note:

Be sure the ST7066U is not in the busy state (BF=00 before sending an instruction from the MPU to the ST7066U. If an instruction is sent without checking the busy flag, the time between the first instruction and next instruction will take much longer than the instruction time itself. Refer to instruction table for the list of each instruction execution time.

12. STANDARD CHARACTER PATTERN (ST7066U-0T)

№. 7066-0T

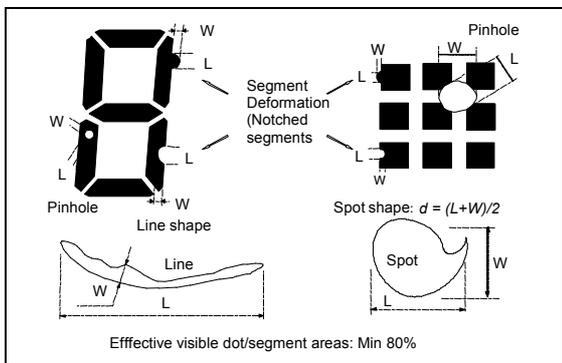
b7-b4 b3-b0	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000	CG RAM (1)			0	1	2	3	4			5	6	7	8	9	0
0001	(2)	!	1	A	0	a	9			7	8	U	1	U	8	
0010	(3)	"	2	B	R	b	r			E	6	E	U	U	8	
0011	(4)	#	3	C	S	c	s			R	E	U	U	2	4	
0100	(5)	\$	4	D	T	d	t			B	r	b	7	6	8	
0101	(6)	%	5	E	U	e	u			R	E	U	U	U	7	
0110	(7)	&	6	F	V	f	v			R	R	U	7	U	8	
0111	(8)	'	7	G	W	g	w			J	S	9	I	I	E	
1000	(1)	(8	H	X	h	x			n	W	U	U	I	7	
1001	(2))	9	I	Y	i	y			V	U	U	7	U	8	
1010	(3)	*	0	J	Z	j	z			U	K	U	U	U	8	
1011	(4)	+	1	K	C	k	c			Y	U	U	U	U	8	
1100	(5)	,	<	L	Q	l	q			U	N	U	U	U	8	
1101	(6)	-	=	M	J	m	j			b	N	C	N	U	8	
1110	(7)	.	>	N	O	n	o			B	n	7	7	U	8	
1111	(8)	/	?	O	L	o	l			a	T	E	.	O	U	

13. QUALITY DESCRIPTION

DEFECT SPECIFICATION:

Specific type-related items are covered in this sheet.

- a: Table for Cosmetic defects
(Note: nc = not counted).
Sizes and number of defects
(Max. Qty)

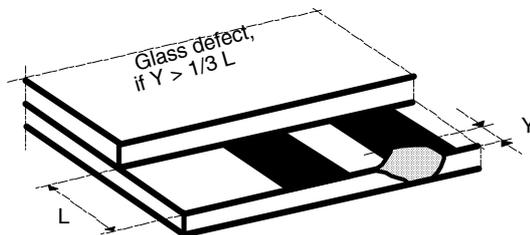


Examples/

Shapes

- b: Glass defects
- b1: Glass defects at contact ledge

b2: Glass chipping in other areas shall not be in conflict



with the product's function.

Defect Type	Max. defect size [μm] d or L W	Max. Quantity.
Black or White Spots	$d \leq 100$	nc
	$100 < d \leq 200$	5
Black or White Lines	-- $W \leq 10$	nc
	$L \leq 5000$ $W \leq 30$	3
	$L \leq 2000$ $W \leq 50$	2
Pinhole	$d \leq 100$ $100 < d \leq 200$	nc 1/segment
	(Total defects)	(5)
Segment Deformation	$W \leq 100$	nc
Bubble (e.g. under pola)	$d \leq 150$	nc
	$200 < d \leq 400$	3
	$400 < d \leq 600$	1

14. MODULE ACCEPT QUALITY LEVEL (AQL)

14.1 AQL Standard Value: Fatal Defect =0.1, Major Defect=0.65; Minor Defect =2.5.

14.2 Curtailed Inspection Scheme

Type	Batch Qty	inspection Qty	AQL value	pass	Reject
module product	350PCS < 1000PCS	125pcs	0.1	0	1
			0.65	2	3
			2.5	7	8
	200PCS < 350PCS	80pcs	0.1	0	1
			0.65	1	2
			2.5	5	6
	<200PCS	32pcs	0.1	0	1
			0.65	0	1
			2.5	4	5
Module sample	<200PCS	All inspected	/	/	The sample will be reject when the fateful defect > 2pcs or main defect > 5pcs.
	>200PCS		125pcs		

- Notes:**
- 1). Batch QTY is the production amount that Production department ship to QA department.
 - 2). All of product will be inspected if the batch QTY less than inspected QTY.
 - 3). Each batch fixed to be 500pcs.

15. RELIABILITY TEST

Operating life time: Longer than 50000 hours

(at room temperature without direct irradiation of sunlight)

Reliability characteristics shall meet following requirements.

TEMPERATURE TESTS	NORMAL GRADE
High temperature storage	+80°C x 96hrs (Without Polarizer)
Low temperature storage	-30°C x 4hrs
High temperature operation	+70°C x 96hrs
Low temperature operation	-20°C x 4hrs
High temperature, High humidity	+70°C x 95%RH x 96hrs (Without Polarizer)
Thermal shock	-20°C x 30min. 10s ↓ 5Cycles +70°C x 30min.
Vibration test	Frequency x Swing x Time 40Hz x 4mm x 4hrs
Drop test	Drop height x Times 1.0m x 6times

16. LCD MODULES HANDLING PRECAUTIONS

- Please remove the protection foil of polarizer before using.
- The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.
- If the display panel is damaged and the liquid crystal substance inside it leaks out, do not get any in your mouth. If the substance come into contact with your skin or clothes promptly wash it off using soap and water.
- Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
- The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarize carefully.
- To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
 - Be sure to ground the body when handling the LCD module.
 - Tools required for assembly, such as soldering irons, must be properly grounded.
 - To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.
 - The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated.
- Storage precautions
When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps. Keep the modules in bags designed to prevent static electricity charging under low temperature / normal humidity conditions (avoid high temperature / high humidity and low temperatures below 0°C).Whenever possible, the LCD modules should be stored in the same conditions in which they were shipped from our company.

17. OTHERS

- Liquid crystals solidify at low temperature (below the storage temperature range) leading to defective orientation of liquid crystal or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subjected to a strong shock at a low temperature.
- If the LCD modules have been operating for a long time showing the same display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. Abnormal operating status can be resumed to be normal condition by suspending use for some time. It should be noted that this phenomena does not adversely affect performance reliability.
- To minimize the performance degradation of the LCD modules resulting from caused by static electricity, etc. exercise care to avoid holding the following sections when handling the modules :
 - Exposed area of the printed circuit board
 - Terminal electrode sections